

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 25 z(axial)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0 \text{ mho/m}$, $\epsilon_r = 1$; $\rho = 0 \text{ kg/m}^3$

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 51.7 dB

ABM1 comp = 3.50 dB A/m

BWC Factor = 0.155979 dB

Location: 7.9, 4.2, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

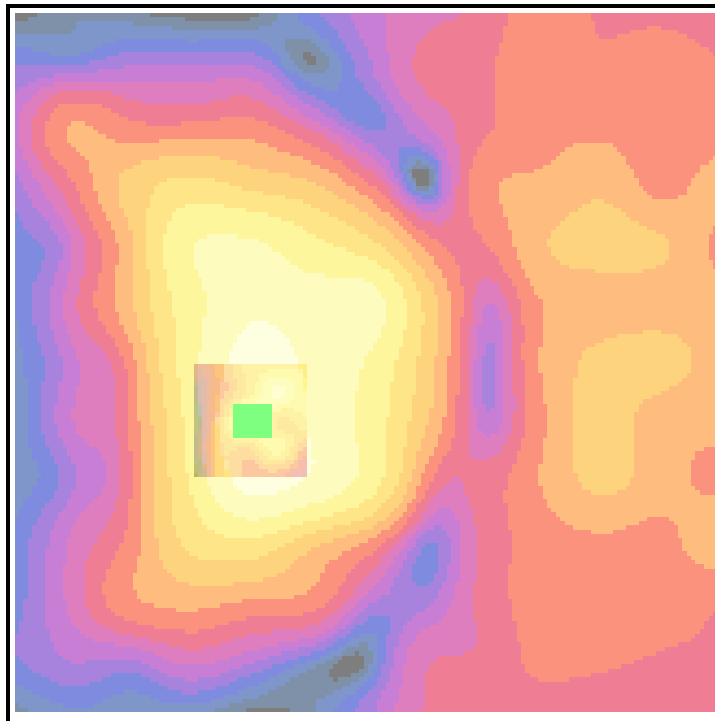
Cursor:

ABM1/ABM2 = 50.9 dB

ABM1 comp = 2.66 dB A/m

BWC Factor = 0.155979 dB

Location: 8.3, 4.2, 3.7 mm



0 dB = 385.4

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 25 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.8 dB

ABM1 comp = -0.058 dB A/m

BWC Factor = 0.155979 dB

Location: -5, -0.4, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

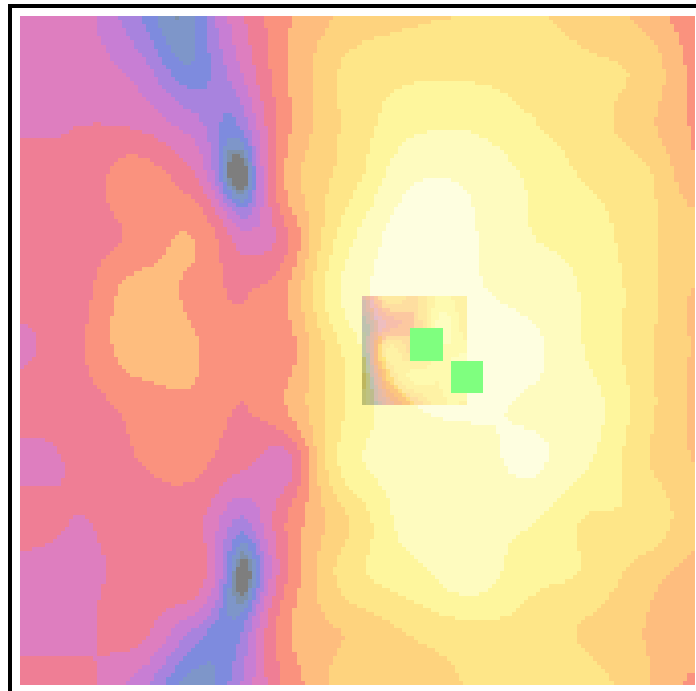
Cursor:

ABM1/ABM2 = 43.5 dB

ABM1 comp = -4.46 dB A/m

BWC Factor = 0.155979 dB

Location: -8.2, 2, 3.7 mm



0 dB = 172.9

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 25 y(transversal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.2 dB

ABM1 comp = -6.48 dB A/m

BWC Factor = 0.155979 dB

Location: 0, -4.6, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

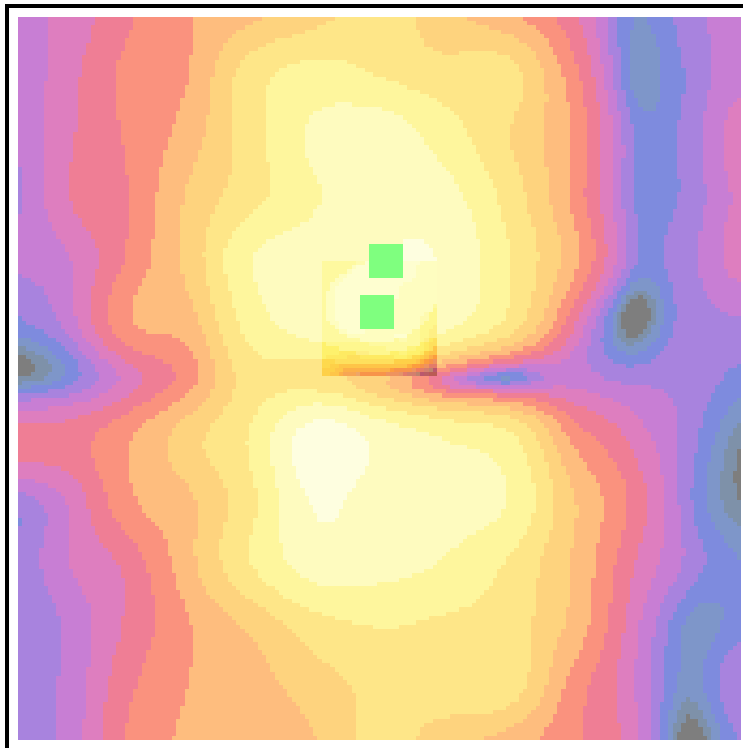
Cursor:

ABM1/ABM2 = 47.2 dB

ABM1 comp = -5.72 dB A/m

BWC Factor = 0.155979 dB

Location: -0.4, -8.2, 3.7 mm



0 dB = 256.0

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 600 z(axial)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C**General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):**

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.1 dB

ABM1 comp = 4.67 dB A/m

BWC Factor = 0.155979 dB

Location: 7.5, 0, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

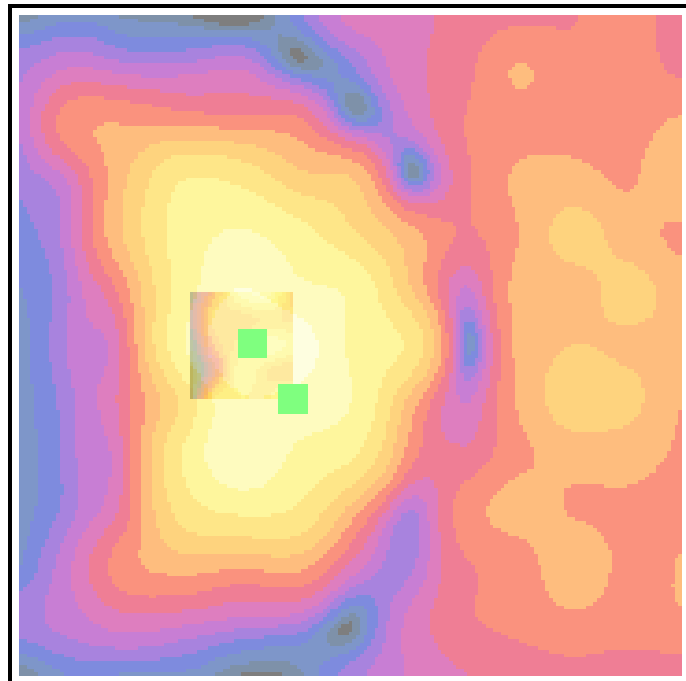
Cursor:

ABM1/ABM2 = 51.3 dB

ABM1 comp = 4.29 dB A/m

BWC Factor = 0.155979 dB

Location: 4.3, 4, 3.7 mm



0 dB = 403.1

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 600 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C**General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):**

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 45.4 dB

ABM1 comp = -3.25 dB A/m

BWC Factor = 0.155979 dB

Location: -8.3, -4.2, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

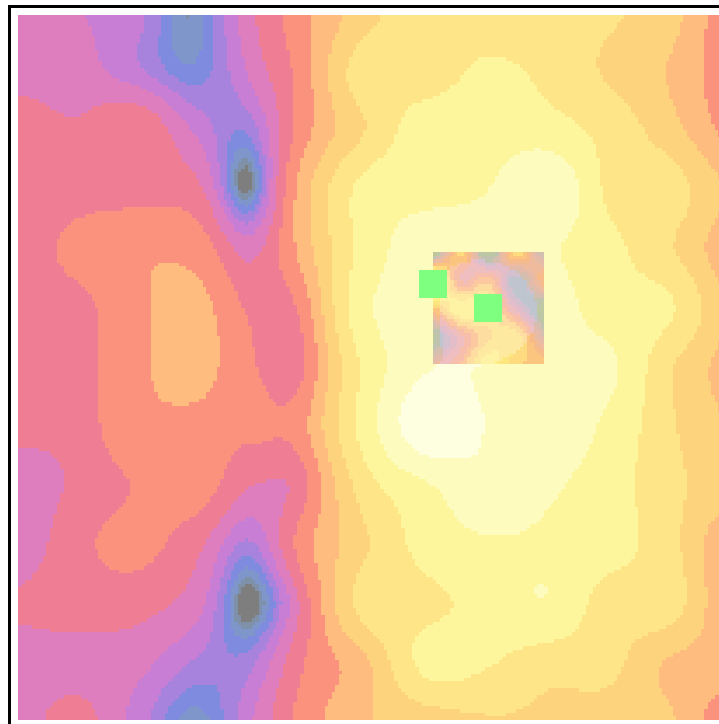
Cursor:

ABM1/ABM2 = 44.5 dB

ABM1 comp = -1.48 dB A/m

BWC Factor = 0.155979 dB

Location: -4.3, -6, 3.7 mm



0 dB = 187.2

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 600 y(transversal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
 Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³
 Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
 Sensor-Surface: 0mm (Fix Surface),
 Electronics: DAE4 Sn602, Calibrated: 6/17/2009
 Measurement SW: DASY4, V4.7 Build 80
 Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 ± 1 deg C, Liquid T = 22.0 ± 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155979 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

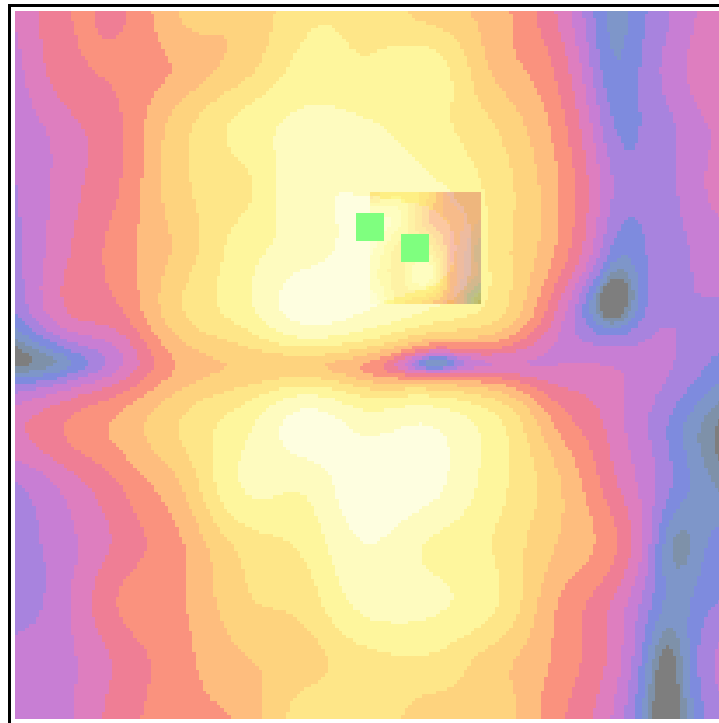
ABM1/ABM2 = 48.1 dB
 ABM1 comp = -7.53 dB A/m
 BWC Factor = 0.155979 dB
 Location: -3.3, -8.3, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155979 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.7 dB
 ABM1 comp = -4.97 dB A/m
 BWC Factor = 0.155979 dB
 Location: -0.2, -9.7, 3.7 mm



0 dB = 255.0

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC T-coil_K33BIC-04_PCS Ch. 1175 z(axial)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 52.5 dB

ABM1 comp = 5.42 dB A/m

BWC Factor = 0.155979 dB

Location: 7.1, 0, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

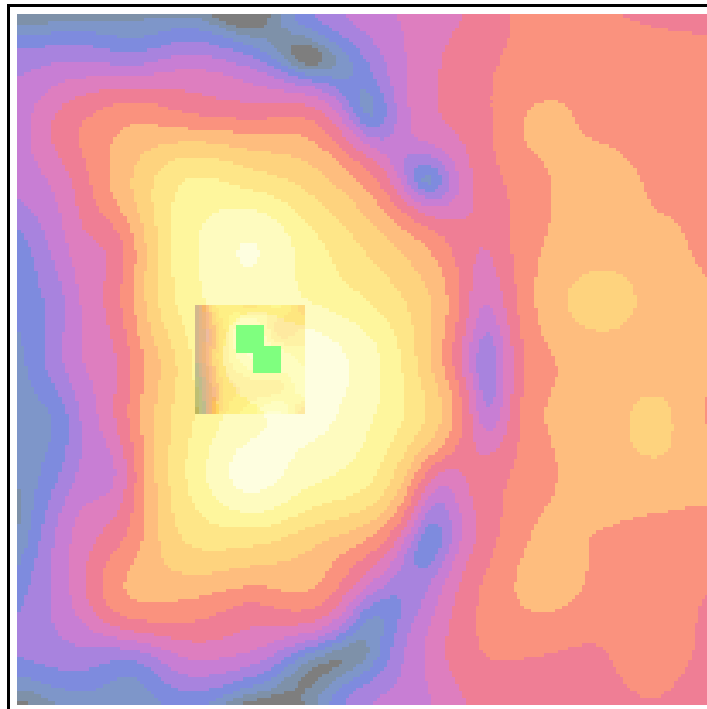
Cursor:

ABM1/ABM2 = 51.2 dB

ABM1 comp = 3.59 dB A/m

BWC Factor = 0.155979 dB

Location: 8.3, -1.6, 3.7 mm



0 dB = 421.0

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 1175 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn602, Calibrated: 6/17/2009

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature: Room T = 21.8 1 deg C, Liquid T = 22.0 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 43.8 dB

ABM1 comp = -7.48 dB A/m

BWC Factor = 0.155979 dB

Location: -11.7, 0, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

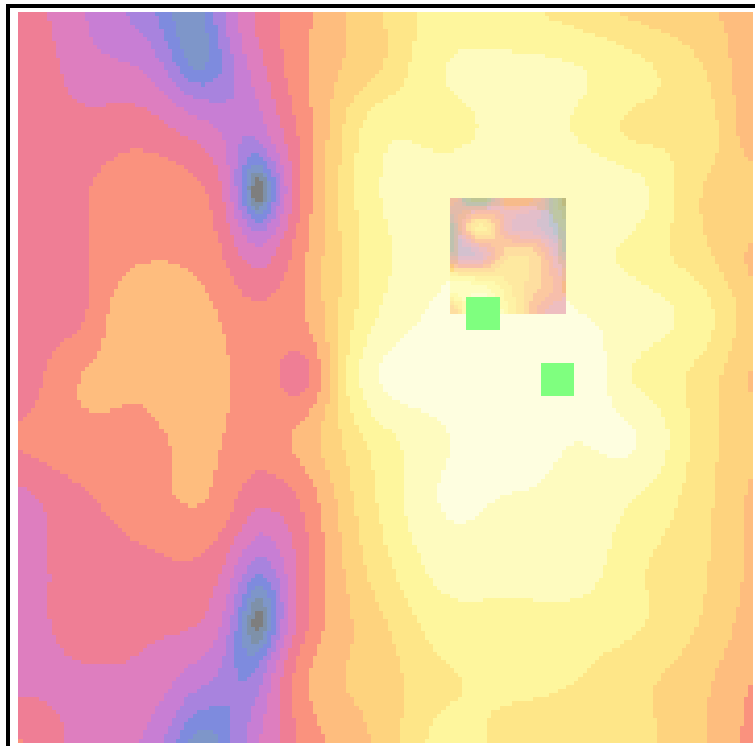
Cursor:

ABM1/ABM2 = 43.4 dB

ABM1 comp = -3.63 dB A/m

BWC Factor = 0.155979 dB

Location: -6.5, -4.3, 3.7 mm



0 dB = 155.7

Test Laboratory: Kyocera

Date: 6/10/2010

FCC C2PC_T-coil_K33BIC-04_PCS Ch. 1175 y(transversal)
 Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
 Medium: T-Coil, Medium parameters used: $\sigma = 0 \text{ mho/m}$, $\epsilon_r = 1$; $\rho = 0 \text{ kg/m}^3$
 Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/22/2009
 Sensor-Surface: 0mm (Fix Surface),
 Electronics: DAE4 Sn602, Calibrated: 6/17/2009
 Measurement SW: DASY4, V4.7 Build 80
 Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8̄ 1 deg C, Liquid T = 22.0̄ 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155979 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

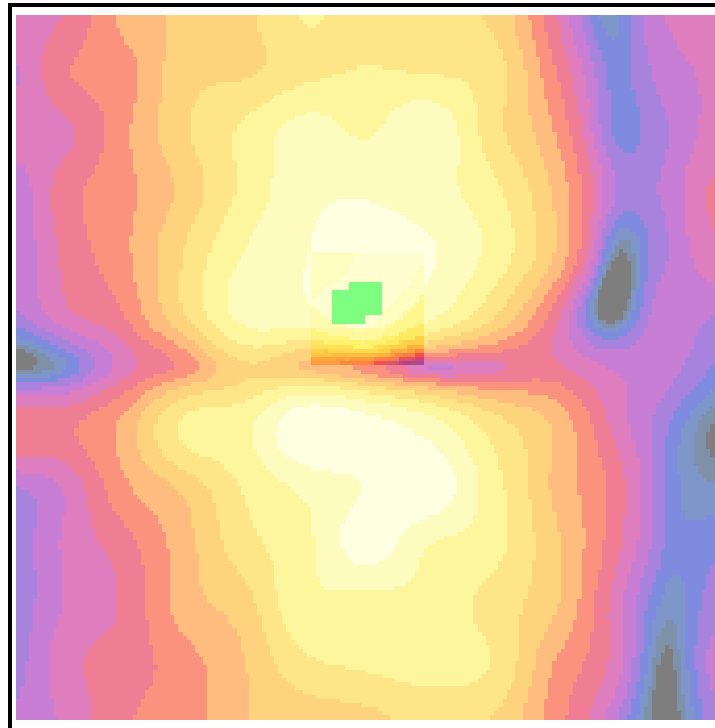
ABM1/ABM2 = 47.4 dB
 ABM1 comp = -7.65 dB A/m
 BWC Factor = 0.155979 dB
 Location: 0, -5, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm
 Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
 BWC applied: 0.155979 dB
 Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.8 dB
 ABM1 comp = -6.51 dB A/m
 BWC Factor = 0.155979 dB
 Location: 1.4, -4.4, 3.7 mm



0 dB = 234.4